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SUBMIT AN ABSTRACT TO:

ELECTRONIC MATERIALS

PHASE STABILITY, PHASE TRANSFORMATIONS, AND REACTIVE PHASE FORMATION IN ELECTRONIC MATERIALS XX

This is the 20th in a series of TMS symposia addressing the stability, transformation, and formation of phases during the fabrication, processing, and utilization of electronic materials and devices. Topics of interests range from microelectronic technologies to advanced energy technologies, including phase stability, transformation, formation, and morphological evolution of electronic packaging materials, interconnection materials, integrated circuit materials, optoelectronic materials as well as energy storage and generating materials.

ORGANIZERS

Hiroshi Nishikawa, Osaka University, Japan
Shih-Kang Lin, National Cheng Kung University, Taiwan
Chao-Hong Wang, National Chung Cheng University, Taiwan
Chih-Ming Chen, National Chung Hsing University, Taiwan

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